



**FOR IMMEDIATE RELEASE**

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**PEMTRON Presents Advanced Semiconductor Inspection Solutions at SEMICON SEA 2025**

April 2025 — PEMTRON, an inspection equipment developer and supplier, is set to exhibit at SEMICON Southeast Asia 2025, taking place May 20-22, 2025 at the Sands Expo and Convention Centre in Singapore. Visitors to Booth L2229 will have the opportunity to experience PEMTRON's latest innovations in wafer, package, and memory module inspection, including the 8800WI Wafer Inspection System, APOLLON Package Inspection System, and MARS High-Speed Memory Module Inspection System.

PEMTRON's advanced inspection systems are designed to address the stringent quality requirements of semiconductor manufacturing, helping manufacturers improve yields, reduce defects, and enhance production efficiency.

**8800WI: Next-Level Wafer Inspection for Precision Defect Detection**

The 8800WI Wafer Inspection System combines state-of-the-art 2D and 3D imaging technologies to detect defects in various bump structures, including micro bumps. Its high-precision imaging allows manufacturers to identify and resolve quality issues at an early stage, ensuring superior yield and product reliability.



**APOLLON: Comprehensive Package Inspection for Maximum Efficiency**

Designed to inspect a wide range of semiconductor packages, including BGA, LGA, QFN, QFP, CSP, and SOP, the APOLLON Package Inspection System enhances manufacturing efficiency with real-time defect detection and automated reporting. By minimizing downtime and maintaining consistent quality standards, APOLLON ensures seamless production workflows for semiconductor packaging.

### **MARS: High-Speed Inspection for Memory Module Manufacturing**

The MARS Automated Visual Inspection (AVI) System is engineered for precision and speed in memory module inspection. Utilizing advanced image processing technology, MARS delivers highly accurate inspection results, even in challenging production environments. Its robust design and rapid processing capabilities make it a key solution for manufacturers aiming to elevate quality control in memory module assembly.

### **Visit PEMTRON at SEMICON SEA 2025**

Attendees are invited to Booth L2229 to see live demonstrations of PEMTRON's advanced inspection systems and learn how these cutting-edge solutions can optimize quality control, enhance production efficiency, and drive manufacturing excellence.

For more information about PEMTRON and its portfolio of inspection systems, visit [www.PEMTRON.com](http://www.PEMTRON.com).

### **About PEMTRON**

Based on 3D precision measurement and vision source technology, PEMTRON develops equipment used in various fields such as SMT, Automotive Field, Lead Tab, Semiconductor, and supplies Soldering Inspection equipment (3D SPI), 3D Mounting Inspection equipment (3D AOI, MOI), Conformal Coating Inspection equipment (TROI-8800 CI), Bottom Head Inspection equipment (Eagle 8800TH), Top & Bottom Double Sided Simultaneous Inspection equipment (Eagle 8800TWIN), Automated X-Ray SMD Counter (MERCURY), Wafer Sawing Before/After 3D Inspection equipment (8800 WI/WIR), Wire Bonding 3D Inspection & MEMS Auto Inspection equipment (ZEUS), Package AVI equipment (APOLLON), Memory Module / SSD Auto Inspection equipment (MARS), FC-BGA, FCP-CSP Inspection equipment (POSEIDON-S), Scale Sorter Of FC-BGA Products (8800 FI), Bump Metal Mask Inspection equipment (8800 MI), PCB Appearance Inspection equipment (8800 AI) and Lead Tab Process/Inspection equipment (Hawk 7300).